

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

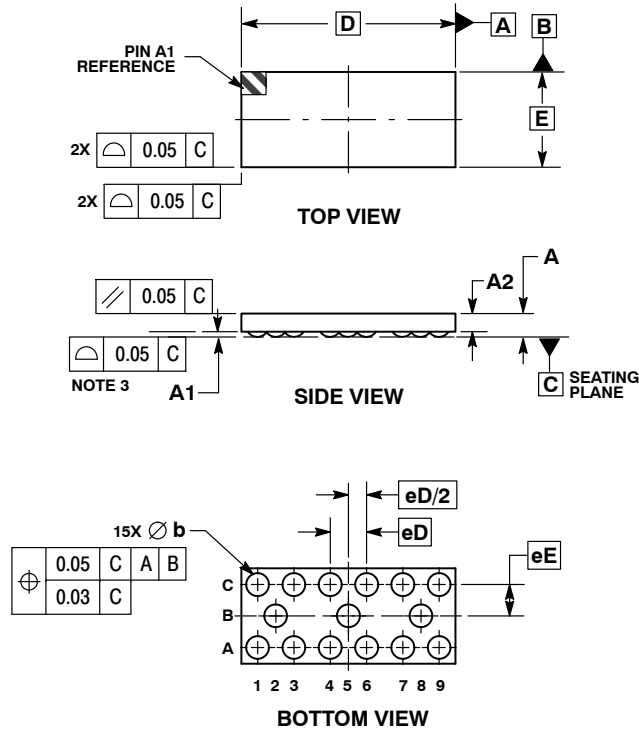
ON Semiconductor®



WLCSP15, 2.36x1.05
CASE 567CM-01
ISSUE O

SCALE 4:1

DATE 26 JUL 2010

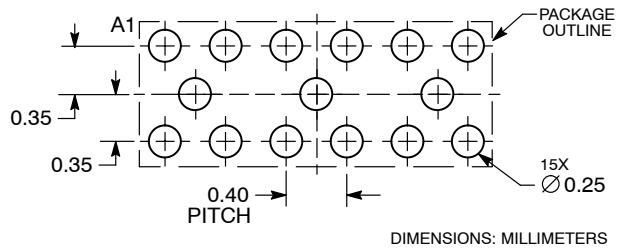


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.22	0.30
A1	0.04	0.12
A2	0.20 REF	
b	0.23	0.28
D	2.36 BSC	
E	1.05 BSC	
eD	0.400 BSC	
eE	0.347 BSC	

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP15, 2.36X1.05	PAGE 1 OF 1

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